

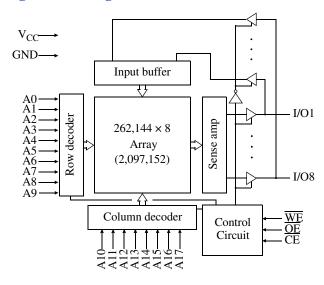
$3.3V 256K \times 8 CMOS SRAM$

Features

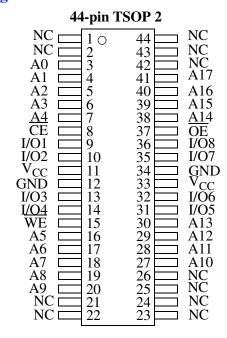
- Industrial and commercial temperature
- Organization: 262,144 words \times 8 bits
- Center power and ground pins
- High speed
 - 10/12/15/20 ns address access time
 - 4/5/6/7 ns output enable access time
- Low power consumption: ACTIVE
- 650 mW / max @ 10 ns
- Low power consumption: STANDBY
 - 28.8 mW / max CMOS

- Equal access and cycle times
- Easy memory expansion with \overline{CE} , \overline{OE} inputs
- TTL-compatible, three-state I/O
- JEDEC standard packages
 - 44-pin TSOP 2
- ESD protection ≥ 2000 volts
- Latch-up current ≥ 200 mA

Logic block diagram



Pin arrangements



Selection guide

		-10	-12	-15	-20	Unit
Maximum address access time	10	12	15	20	ns	
Maximum output enable access time	4	5	6	7	ns	
Maximum operating current	Industrial	180	160	140	110	mA
Waximum operating current	Commercial	170	150	130	100	mA
Maximum CMOS standby current	8	8	8	8	mA	



Functional description

The AS7C32096A is a high-performance CMOS 2,097,152-bit Static Random Access Memory (SRAM) device organized as 262,144 words × 8 bits. It is designed for memory applications where fast data access, low power, and simple interfacing are desired.

Equal address access and cycle times (t_{AA} , t_{RC} , t_{WC}) of 10/12/15/20 ns with output enable access times (t_{OE}) of 4/5/6/7 ns are ideal for high-performance applications. The chip enable input \overline{CE} permits easy memory expansion with multiple-bank memory systems.

When $\overline{\text{CE}}$ is high the device enters standby mode. The device is guaranteed not to exceed 28.8mW power consumption in CMOS standby mode.

A write cycle is accomplished by asserting write enable (\overline{WE}) and chip enable (\overline{CE}) . Data on the input pins I/O1–I/O8 is written on the rising edge of \overline{WE} (write cycle 1) or \overline{CE} (write cycle 2). To avoid bus contention, external devices should drive I/O pins only after outputs have been disabled with output enable (\overline{OE}) or write enable (\overline{WE}) .

A read cycle is accomplished by asserting output enable (\overline{OE}) and chip enable (\overline{CE}) , with write enable (\overline{WE}) high. The chip drives I/O pins with the data word referenced by the input address. When either chip enable or output enable is inactive, or write enable is active, output drivers stay in high-impedance mode.

All chip inputs and outputs are TTL-compatible, and operation is from a single 3.3V supply voltage. This device is available as per industry standard 44-pin TSOP 2 package.

Absolute maximum ratings

Parameter	Symbol	Min	Max	Unit
Voltage on V _{CC} relative to GND	V _{t1}	-0.5	+5.0	V
Voltage on any pin relative to GND	V_{t2}	-0.5	V _{CC} +0.5	V
Power dissipation	P_{D}	_	1.0	W
Storage temperature (plastic)	T_{stg}	-65	+150	°C
Temperature with V _{CC} applied	T _{bias}	-55	+125	°C
DC current into output (low)	I_{OUT}	_	20	mA

NOTE: Stresses greater than those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions outside those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

Truth table

CE	$\overline{ ext{WE}}$	$\overline{\mathbf{OE}}$	Data	Mode
Н	X	X	High Z	Standby (I _{SB} , I _{SB1})
L	Н	Н	High Z	Output disable (I _{CC})
L	Н	L	D_{OUT}	Read (I _{CC})
L	L	X	D_{IN}	Write (I _{CC})

Key: X = Don't care, L = Low, H = High



Recommended operating condition

Param	eter	Symbol	Min	Nominal	Max	Unit
Supply voltage		V _{CC} (10/12/15/20)	3.0	3.3	3.6	V
Input voltage		V _{IH} **	2.0	_	$V_{CC} + 0.5$	V
input voltage	Input voltage		-0.5	_	0.8	V
Ambient operating	commercial	T _A	0	-	70	°C
temperature	industrial	T_A	-40	_	85	°C

DC operating characteristics (over the operating range) I

				- 1	10	_1	12	-15		-2	20	
Parameter	Symbol	Test conditions		Min	Max	Min	Max	Min	Max	Min	Max	Unit
Input leakage current	II _{LI} I	$V_{CC} = Max$, $V_{IN} = GND$ to V_{CC}		ı	1	ı	1	ı	1	ı	1	μΑ
Output leakage current	II _{LO} I	$V_{CC} = Max, \overline{CE} = V_{IH}$ $V_{OUT} = GND \text{ to } V_{CC}$		ĺ	1	ĺ	1	ĺ	1	ĺ	1	μΑ
Operating power	I_{CC}	$V_{CC} = Max, \overline{CE} \le V_{II}$	Industrial	-	180	-	160	-	140	-	110	mA
supply current	100	$f = f_{Max}, I_{OUT} = 0mA$	Commercial	-	170	-	150	-	130	-	100	mA
	I_{SB}	$V_{CC} = Max, \overline{CE} \ge V_{IH, f}$	= f _{Max}	ı	60	ı	60	ı	60	ı	60	mA
Standby power supply current	I _{SB1}	$\begin{aligned} & V_{CC} = Max, \\ & \overline{CE} \ge V_{CC} - 0.2V, \\ & V_{IN} \le 0.2V \text{ or } V_{IN} \ge V_{CC} \\ & f = 0 \end{aligned}$		1	8	ı	8	ı	8	ı	8	mA
Output voltage	V_{OL} $I_{OL} = 8 \text{ mA}, V_{CC} = \text{Min}$		ı	0.4	ı	0.4	ı	0.4	ı	0.4	V	
Output Voltage	V _{OH}	$I_{OH} = -4 \text{ mA}, V_{CC} = 1$	Min	2.4	_	2.4	_	2.4	_	2.4	_	V

Capacitance (f = 1MHz, $T_a = 25^{\circ}$ C, $V_{CC} = NOMINAL)^4$

Parameter	Symbol	Signals	Test conditions	Max	Unit
Input capacitance	C_{IN}	$A, \overline{CE}, \overline{WE}, \overline{OE}$	$V_{IN} = 0V$	5	pF
I/O capacitance	C _{I/O}	I/O	$V_{IN} = V_{OUT} = 0V$	7	pF

 $V_{\rm IL}$ min = -1.0V for pulse width less than 5ns. $V_{\rm IH}$ max = $V_{\rm CC}$ + 2.0V for pulse width less than 5ns.



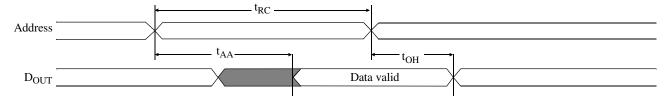
Read cycle (over the operating range)^{2,8}

		-	10	-1	12	-	15	-2	20		
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Min	Max	Unit	Notes
Read cycle time	t _{RC}	10	_	12	_	15	-	20	_	ns	
Address access time	t_{AA}	-	10	_	12	_	15	-	20	ns	2
Chip enable (CE) access time	t _{ACE}	-	10	_	12	_	15	-	20	ns	2
Output enable (OE) access time	t _{OE}	-	4	_	5	_	6	_	7	ns	
Output hold from address change	t _{OH}	3	_	3	_	3	-	3	_	ns	4
CE Low to output in low Z	t _{CLZ}	3	_	3	_	3	-	3	_	ns	3,4
CE High to output in high Z	t _{CHZ}	-	5	_	6	_	7	-	9	ns	3,4
OE Low to output in low Z	t _{OLZ}	0	_	0	_	0	-	0	_	ns	3,4
OE High to output in high Z	t _{OHZ}	-	5	_	6	_	7	-	9	ns	3,4
Power up time	t _{PU}	0	_	0	_	0	-	0	_	ns	3,4
Power down time	t _{PD}	_	10	-	12	-	15	-	20	ns	3,4

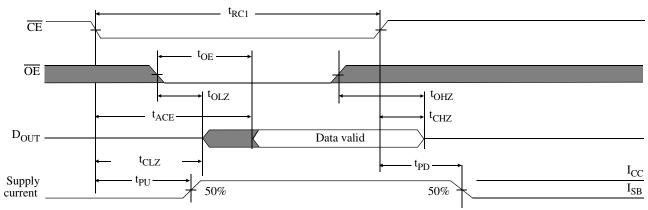
Key to switching waveforms

Rising input Falling input Undefined/don't care

Read waveform 1 (address controlled)^{2,5,6,8}



Read waveform 2 (CE, OE controlled)^{2,5,7,8}



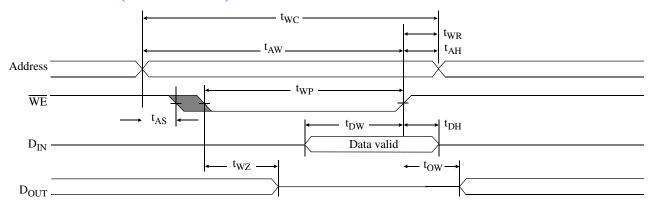
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Write cycle (over the operating range)⁹

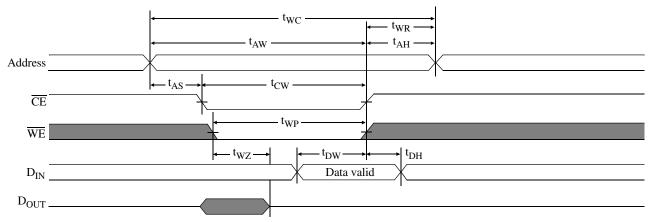
		-	10	-1	12	-1	15	-2	20		
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Min	Max	Unit	Notes
Write cycle time	t _{WC}	10	_	12	_	15	-	20	_	ns	
Chip enable (\overline{CE}) to write end	t _{CW}	7	_	8	_	10	-	12	_	ns	
Address setup to write end	t _{AW}	7	-	8	-	10	-	12	-	ns	
Address setup time	t _{AS}	0	_	0	_	0	-	0	_	ns	
Write pulse width $(\overline{OE} = high)$	t _{WP1}	7	_	8	_	10	-	12	_	ns	
Write pulse width $(\overline{OE} = low)$	t _{WP2}	10	_	12	_	15	-	20	_	ns	
Address hold from end of write	t _{AH}	0	-	0	_	0	_	0	_	ns	
Write recovery time	t _{WR}	0	_	0	_	0	-	0	_	ns	
Data valid to write end	t_{DW}	5	_	6	_	7	-	9	_	ns	
Data hold time	t _{DH}	0	-	0	_	0	_	0	-	ns	3,4
Write enable to output in high Z	t _{WZ}	0	5	0	6	0	7	0	9	ns	3,4
Output active from write end	t _{OW}	3	-	3	_	3	_	3	-	ns	3,4

Write waveform 1 (WE controlled)9



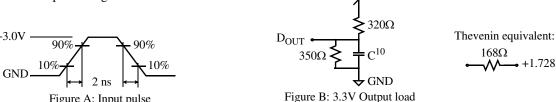


Write waveform 2 (CE controlled)9



AC test conditions

- Output load: see Figure B.
- Input pulse level: GND to 3.0V. See Figures A and B.
- Input rise and fall times: 2 ns. See Figure A.
- Input and output timing reference levels: 1.5V.



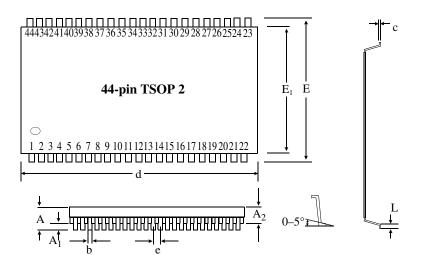
 D_{OUT}

Notes

- During V_{CC} power-up, a pull-up resistor to V_{CC} on \overline{CE} is required to meet I_{SB} specification. 1
- For test conditions, see AC Test Conditions.
- t_{CLZ} and t_{CHZ} are specified with $C_L = 5 pF$ as in Figure B. Transition is measured ± 500 mV from steady-state voltage. 3
- This parameter is guaranteed, but not tested. 4
- $\overline{\text{WE}}$ is HIGH for read cycle. 5
- $\overline{\text{CE}}$ and $\overline{\text{OE}}$ are LOW for read cycle. 6
- Address valid prior to or coincident with $\overline{\text{CE}}$ transition Low. 7
- All read cycle timings are referenced from the last valid address to the first transitioning address.
- 9 All write cycle timings are referenced from the last valid address to the first transitioning address.
- 10 C=30pF, except on High Z and Low Z parameters, where C=5pF.



Package dimensions



	44-pin	TSOP 2			
	Min(mm)	Max(mm)			
A		1.2			
A ₁	0.05	0.15			
A ₂	0.95	1.05			
b	0.30	0.45			
c	0.12	0.21			
d	18.31	18.52			
\mathbf{E}_1	10.06	10.26			
E	11.68	11.94			
e	0.80 (typical)				
L	0.40	0.60			



Ordering codes

Package	Temperature	10 ns	12 ns	15 ns	20 ns
TSOP 2	Commercial	AS7C32096A-10TC	AS7C32096A-12TC	AS7C32096A-15TC	AS7C32096A-20TC
1501 2	Industrial	AS7C32096A-10TI	AS7C32096A-12TI	AS7C32096A-15TI	AS7C32096A-20TI

Note: Add suffix 'N' to the above part number for Lead Free Parts. (Ex: AS7C32096A - 10TIN)

Part numbering system

AS7C	X	2096A	–XX	T	X	X
SRAM prefix	Voltage: 3 - 3.3V CMOS	Device number	Access time	Package: T: TSOP 2	Temperature ranges: C: Commercial, 0°C to 70°C I: Industrial, –40°C to 85°C	





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